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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Pirmin Gerhard MUFFLER

Serial No.: 09/727,354

Group No.: 1733

Filing Date: 30 November 2000

Examiner: Jessica Rossi

Title: METHOD FOR APPLYING A SUBSTRATE

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

RECEIVED
NOV 22 2002
TC 1700

Dear Sir:

In response to the Office Action mailed 13 June 2002, please amend the subject Patent Application as follows:

In the Specification:

At Page 3, lines 1-11:

B)

PCT International Publication WO 99/25019 describes a special mixture for mounting and disassembling a semiconductor wafer. German Patent Reference DE 43 32 488 discloses a foil attached as flat as possible by adhesive force. Also known are reversible adhesive layers. It has become apparent, that despite expensive preparation of the wafer substrate, there is an inherent disadvantage in the system.

I hereby certify that this correspondence (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on

13 NOV 2002

13 Nov 02

Date

Signature